

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

1. (Canceled)
2. (Previously Presented) The manufacturing method according to claim 15, wherein the increasing comprises disposing a casing comprising at least one bottom half-shell at least under the contact pads.
3. (Previously Presented) The manufacturing method according to claim 2, further comprising interfitting the bottom half-shell with a top half-shell covering a zone of the microcircuit that lies outside the contact pads.
4. (Previously Presented) The manufacturing method according to claim 15, wherein the increasing comprises inserting the microcircuit into a shell having an access on a rear edge.
5. (Previously Presented) The manufacturing method according to claim 15, wherein the increasing comprises forming an overmolded portion over the microcircuit.

6. (Previously Presented) The manufacturing method according to claim 2, further comprising fastening the microcircuit to the bottom half-shell.

7. (Previously Presented) The manufacturing method according to claim 6, wherein the fastening is by adhesive bonding or by tight-fitting cross-wise at least.

8. (Previously Presented) The manufacturing method according to claim 15, wherein the electronic component is disposed at a location offset from a location of the contact pads.

9. (Previously Presented) The manufacturing method according to claim 15, wherein the electronic component is disposed on the same top face of the microcircuit as the contact pads.

10 - 14. (Canceled)

15. (Previously Presented) A method for manufacturing a USB electronic key, comprising cutting out, from a dielectric backing film which has a thickness of less than or equal to 200 μm and carries a plurality of microcircuits, a portion of the dielectric backing film including one of the microcircuits, each microcircuit defining USB-format contact pads and carrying an electronic component connected to the pads; and, in a single operation, increasing the thickness of the cut-out portion of the dielectric backing film including the one of the microcircuits at least in the area of the

contact pads of the one of the microcircuits, so as to have a thickness that conforms to the USB Standard.

16. (Currently Amended) A method for manufacturing a USB electronic key from a dielectric backing film which carries a microcircuit, the microcircuit defining USB-format contact pads and carrying an electronic component connected to the pads, the method comprising, in a single operation, increasing the thickness of the dielectric backing film including the microcircuit at least in the area of the contact pads of the microcircuit, so as to have a thickness that conforms to the USB Standard, wherein the increasing comprises disposing at least the contact pads in a cavity of a casing.

17. (Canceled)

18. (Currently Amended) The manufacturing method according to claim ~~[[17]]~~ 16, wherein the cavity is provided in a bottom half-shell of the casing, the method further comprising interfitting the bottom half-shell with a top half-shell covering to thereby cover the bottom-half shell only on a zone of the microcircuit that lies outside side opposite a side of the bottom-half shell which contains the contact pads.

19. (Currently Amended) The manufacturing method according to claim 16, wherein the increasing further comprises inserting the microcircuit into ~~a shell having~~ an access on a rear edge of the casing.

20. (Currently Amended) The manufacturing method according to claim 16, wherein the increasing further comprises forming an overmolded portion over the microcircuit.

21. (Currently Amended) The manufacturing method according to claim ~~[[17]]~~ 18, further comprising fastening the microcircuit to the bottom half-shell.

22. (Previously Presented) The manufacturing method according to claim 21, wherein the fastening is by adhesive bonding or by tight-fitting cross-wise at least.

23. (Previously Presented) The manufacturing method according to claim 16, wherein the electronic component is disposed at a location offset from a location of the contact pads.

24. (Previously Presented) The manufacturing method according to claim 16, wherein the electronic component is disposed on the same top face of the microcircuit as the contact pads.

25. (Previously Presented) The manufacturing method according to claim 16, wherein the dielectric backing film has a thickness of less than or equal to 200 μm .

26. (Currently Amended) A method for manufacturing a USB electronic key from an insulating substrate which carries a microcircuit, the microcircuit defining

USB-format contact pads and carrying an electronic component connected to the pads, the method comprising, in a single operation, increasing the thickness of the insulating substrate including the microcircuit at least in the area of the contact pads of the microcircuit, so as to have a thickness that conforms to the USB Standard, wherein the increasing comprises disposing at least the contact pads in a cavity of a casing.

27. (New) A method for manufacturing a USB electronic key from a dielectric backing film or insulating substrate which carries a microcircuit, the microcircuit defining USB-format contact pads and carrying an electronic component connected to the pads, the method comprising disposing a bottom-half shell and a top-half shell at the dielectric backing film or insulating substrate such that the bottom-half shell is below the dielectric backing film or insulating substrate and the top-half shell is above the dielectric backing film or insulating substrate, to thereby increase the thickness of the dielectric backing film or insulating substrate at least in the area of the contact pads of the microcircuit, wherein the top-half shell covers only one side of the bottom-half shell opposite a side at which the contact pads are disposed.